Product Change Notification - KSRA-04FJDK272

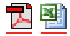
Date:

18 Oct 2018

Product Category:

8-bit Microcontrollers

Affected CPNs:



Notification subject:

CCB 2937 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L QFN-S package at NSEB assembly site

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L QFN-S package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8600 die attach and G700LTD mold compound material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

	Pre Change	**Post Change**
Assembly Site	NSEB Assembly Site	NSEB Assembly Site
Wire material	Au Wire	CuPdAu Wire
Die attach material	8600	8600
Molding compound material	G700LTD	G700LTD
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

November 18, 2018 (date code: 1847)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and

post change parts.

Time Table Summary:

	May 2017					-->	October 2018				November 2018				
Workweek	18	19	20	21	22		40	41	42	43	44	45	46	47	48
Initial PCN Issue Date		X													
Qual Report Availability									X						
Final PCN Issue Date									X						
Estimated Implementation Date														X	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report

Revision History:

May 09, 2017: Issued initial notification.

October 18, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on November 18, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-04FJDK272_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers(CPN)

PIC18F25K80-E/MM
PIC18F25K80-E/MMC01
PIC18F25K80-H/MM
PIC18F25K80-I/MM
PIC18F25K80-I/MM030
PIC18F25K80-I/MM031
PIC18F25K80-I/MM032
PIC18F25K80-I/MMC04
PIC18F25K80T-E/MM
PIC18F25K80T-E/MMC01
PIC18F25K80T-E/MMCUI
PIC18F25K80T-H/MM
PIC18F25K80T-I/MM
PIC18F25K80T-I/MM030
PIC18F25K80T-I/MM031
PIC18F25K80T-I/MM032
PIC18F25K80T-I/MMC04
PIC18F26K80-E/MM
PIC18F26K80-H/MM
PIC18F26K80-I/MM
PIC18F26K80T-E/MM
PIC18F26K80T-I/MM
PIC18F26K80T-I/MM023
PIC18F26K80T-I/MM025
PIC18LF25K80-I/MM
PIC18LF25K80T-I/MM
PIC18LF26K80-I/MM
PIC18LF26K80-I/MMC01
PIC18LF26K80T-I/MM
PIC18LF26K80T-I/MMC01